



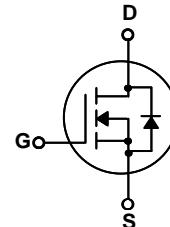
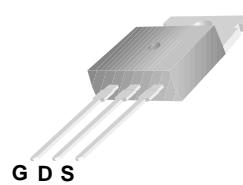
Wisdom Technologies Int'l

WFP10N60

600V N-Channel MOSFET

Features

- Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Extended Safe Operating Area
- Unrivalled Gate Charge : $Q_g = 33\text{nC}$ (Typ.)
- $\text{BVDSS}=600\text{V}, \text{ID}=10\text{A}$
- $R_{DS(on)} : 0.73 \Omega$ (Max) @ $\text{VG}=10\text{V}$
- 100% Avalanche Tested



TO-220

G-Gate,D-Drain,S-Source

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | WFP10N60 | Units |
|----------------|--|------------|-------|
| V_{DSS} | Drain-Source Voltage | 600 | V |
| I_D | Drain Current -continuous ($T_c=25^\circ\text{C}$) | 10 | A |
| | -continuous ($T_c=100^\circ\text{C}$) | 3.4 | A |
| V_{GS} | Gate-Source Voltage | ± 30 | V |
| E_{AS} | Single Plused Avalanche Energy (Note1) | 520 | mJ |
| I_{AR} | Avalanche Current (Note2) | 10 | A |
| P_D | Power Dissipation ($T_c=25^\circ\text{C}$) | 156 | W |
| T_J, T_{STG} | Operating and Storage Temperature Range | -55 ~ +150 | °C |
| T_L | Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds | 300 | °C |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max | Units |
|-----------------|--|------|------|-------|
| $R_{\theta JC}$ | Thermal Resistance,Junction to Case | -- | 0.8 | °C/W |
| $R_{\theta CS}$ | Thermal Resistance,Case to Sink | 0.5 | -- | °C/W |
| $R_{\theta JA}$ | Thermal Resistance,Junction to Ambient | -- | 62.5 | °C/W |

Electrical Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Test Condition | Min. | Typ. | Max | Units |
|--|---|--|------|------|------|---------------------------|
| Off Characteristics | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $\text{ID}=250 \mu\text{A}, \text{VGS}=0$ | 600 | -- | -- | V |
| $\Delta \text{BV}_{\text{DSS}}/\Delta T_J$ | Breakdown Voltage Temperature Coefficient | $\text{I}_D=250 \mu\text{A}$, Reference to 25°C | -- | 0.7 | -- | $\text{V}/^\circ\text{C}$ |
| IDSS | Zero Gate Voltage Drain Current | $\text{Vds}=600\text{V}, \text{Vgs}=0\text{V}$ | -- | -- | 1 | μA |
| | | $\text{Vds}=480\text{V}, \text{Tc}=125^\circ\text{C}$ | | | 10 | μA |
| IGSSF | Gate-body leakage Current, Forward | $\text{Vgs}=+30\text{V}, \text{Vds}=0\text{V}$ | -- | -- | 100 | nA |
| IGSSR | Gate-body leakage Current, Reverse | $\text{Vgs}=-30\text{V}, \text{Vds}=0\text{V}$ | -- | -- | -100 | nA |

On Characteristics

| | | | | | | |
|----------------------------|-----------------------------------|---|----|----|------|----------|
| $\text{V}_{\text{GS(th)}}$ | Date Threshold Voltage | $\text{Id}=250\mu\text{A}, \text{Vds}=\text{Vgs}$ | 2 | -- | 4 | V |
| $\text{R}_{\text{DS(on)}}$ | Static Drain-Source On-Resistance | $\text{Id}=5\text{A}, \text{Vgs}=10\text{V}$ | -- | -- | 0.73 | Ω |

Dynamic Characteristics

| | | | | | | |
|------|------------------------------|--------------------------------------|----|------|------|----|
| Ciss | Input Capacitance | VDS=25V, VGS=0, $f=1.0\text{MHz}$ | -- | 1570 | 2040 | pF |
| Coss | Output Capacitance | | -- | 166 | 215 | pF |
| Crss | Reverse Transfer Capacitance | | -- | 18 | 24 | pF |

Switching Characteristics

| | | | | | | |
|---------|---------------------|--|----|------|-----|----|
| Td(on) | Turn-On Delay Time | VDD=300V, ID=10A $RG=25\Omega$ (Note 3,4) | -- | 23 | 55 | nS |
| Tr | Turn-On Rise Time | | -- | 66 | 150 | nS |
| Td(off) | Turn-Off Delay Time | | -- | 144 | 300 | nS |
| Tf | Turn-Off Fall Time | | -- | 77 | 165 | nS |
| Qg | Total Gate Charge | VDS=480, VGS=10V, ID=10A (Note 3,4) | -- | 44 | 57 | nC |
| Qgs | Gate-Source Charge | | -- | 6.7 | -- | nC |
| Qgd | Gate-Drain Charge | | -- | 18.5 | -- | nC |

Drain-Source Diode Characteristics and Maximum Ratings

| | | | | | | |
|-----------------|---|--|----|-----|-----|---------------|
| I _S | Maximum Continuous Drain-Source Diode Forward Current | -- | -- | 10 | A | |
| I _{SM} | Maximum Plused Drain-Source DiodeForwad Current | -- | -- | | A | |
| V _{SD} | Drain-Source Diode Forward Voltage | $\text{Id}=10\text{A}$ | -- | -- | 1.4 | V |
| trr | Reverse Recovery Time | $\text{I}_S=10\text{A}, \text{V}_{\text{GS}}=0\text{V}$ $d\text{I}/dt=100\text{A}/\mu\text{s}$ (Note 3) | -- | 340 | -- | nS |
| Qrr | Reverse Recovery Charge | | -- | 3.2 | -- | μC |

*Notes 1, L=10.6mH, IAS=9.5A, VDD=50V, RG=25Ω, Starting TJ =25°C

2, Repetitive Rating : Pulse width limited by maximum junction temperature

3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%

4, Essentially Independent of Operating Temperature

Typical Characteristics

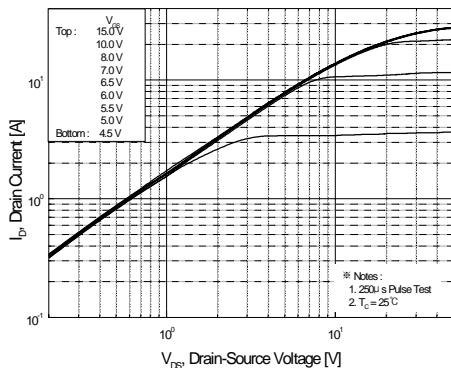


Figure 1. On-Region Characteristics

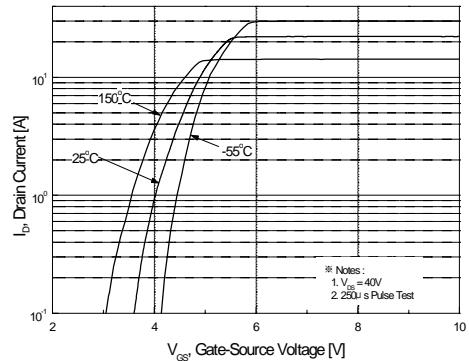


Figure 2. Transfer Characteristics

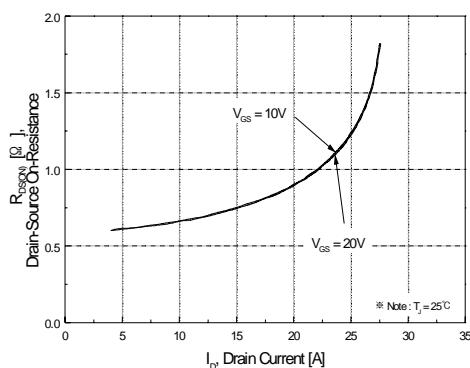


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

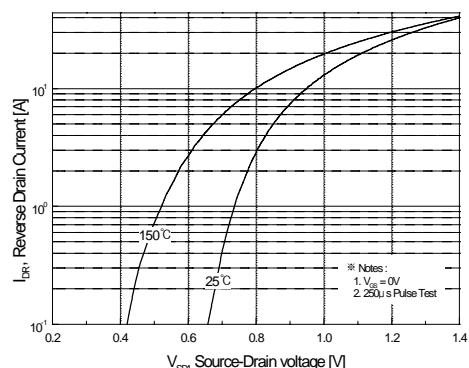


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

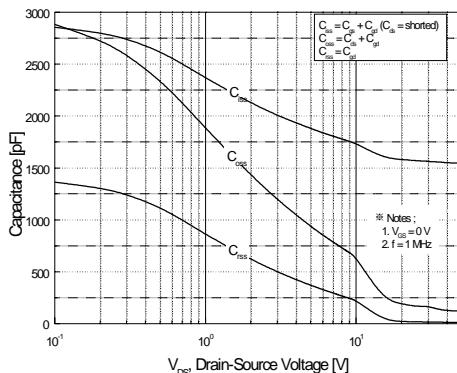


Figure 5. Capacitance Characteristics

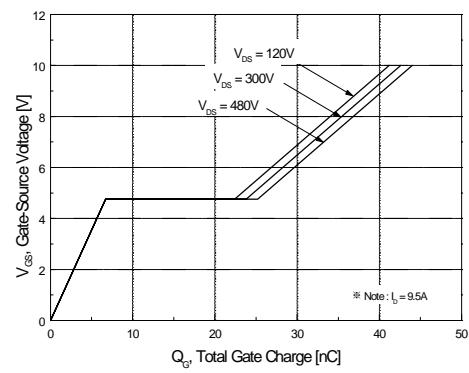
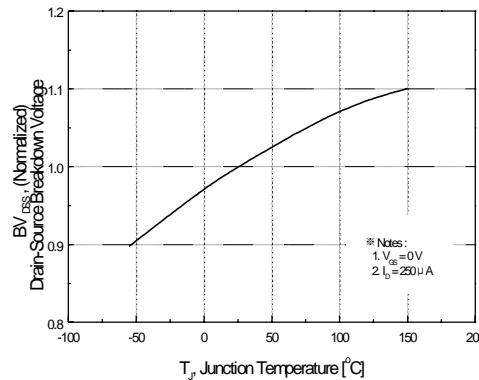
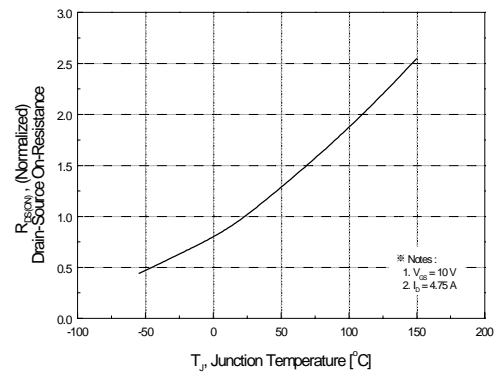


Figure 6. Gate Charge Characteristics

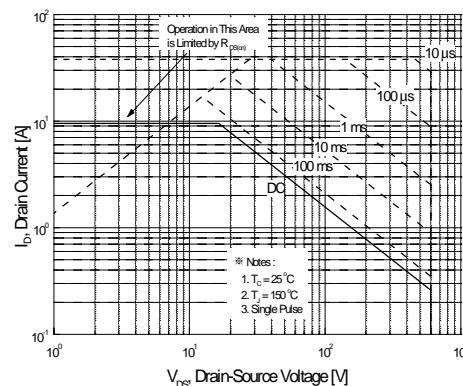
Typical Characteristics (Continued)



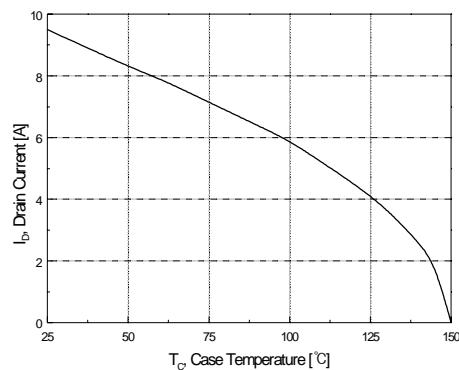
**Figure 7. Breakdown Voltage Variation
vs Temperature**



**Figure 8. On-Resistance Variation
vs Temperature**



**Figure 9-1. Maximum Safe Operating Area
for WFP10N60**



**Figure 10. Maximum Drain Current
vs Case Temperature**

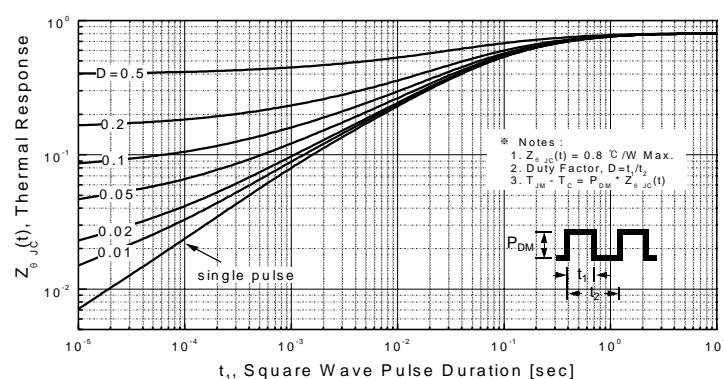
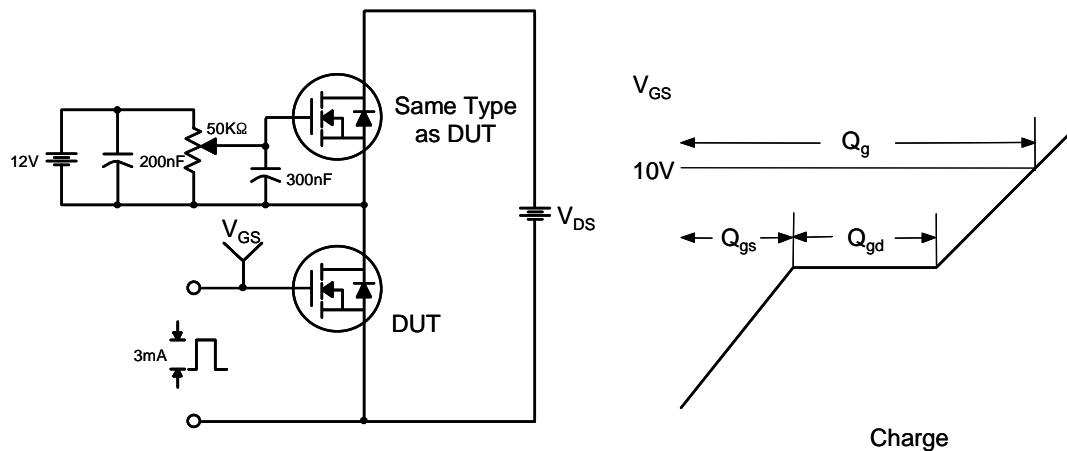
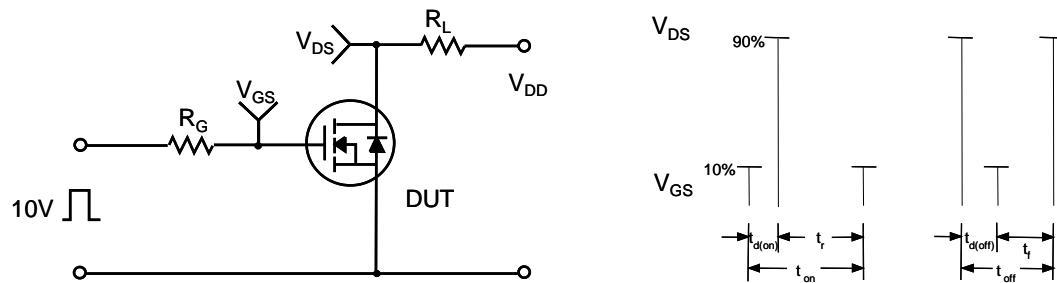
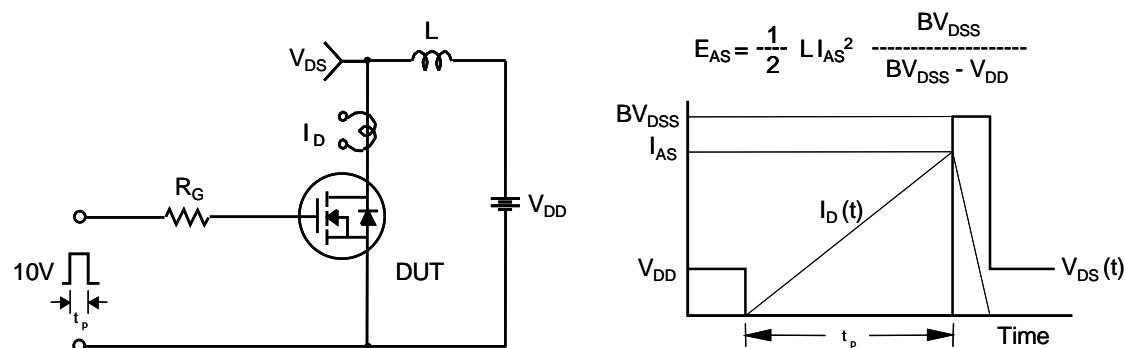


Figure 11-1. Transient Thermal Response Curve for WFP10N60

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching Test Circuit & Waveforms


Peak Diode Recovery dv/dt Test Circuit & Waveforms

